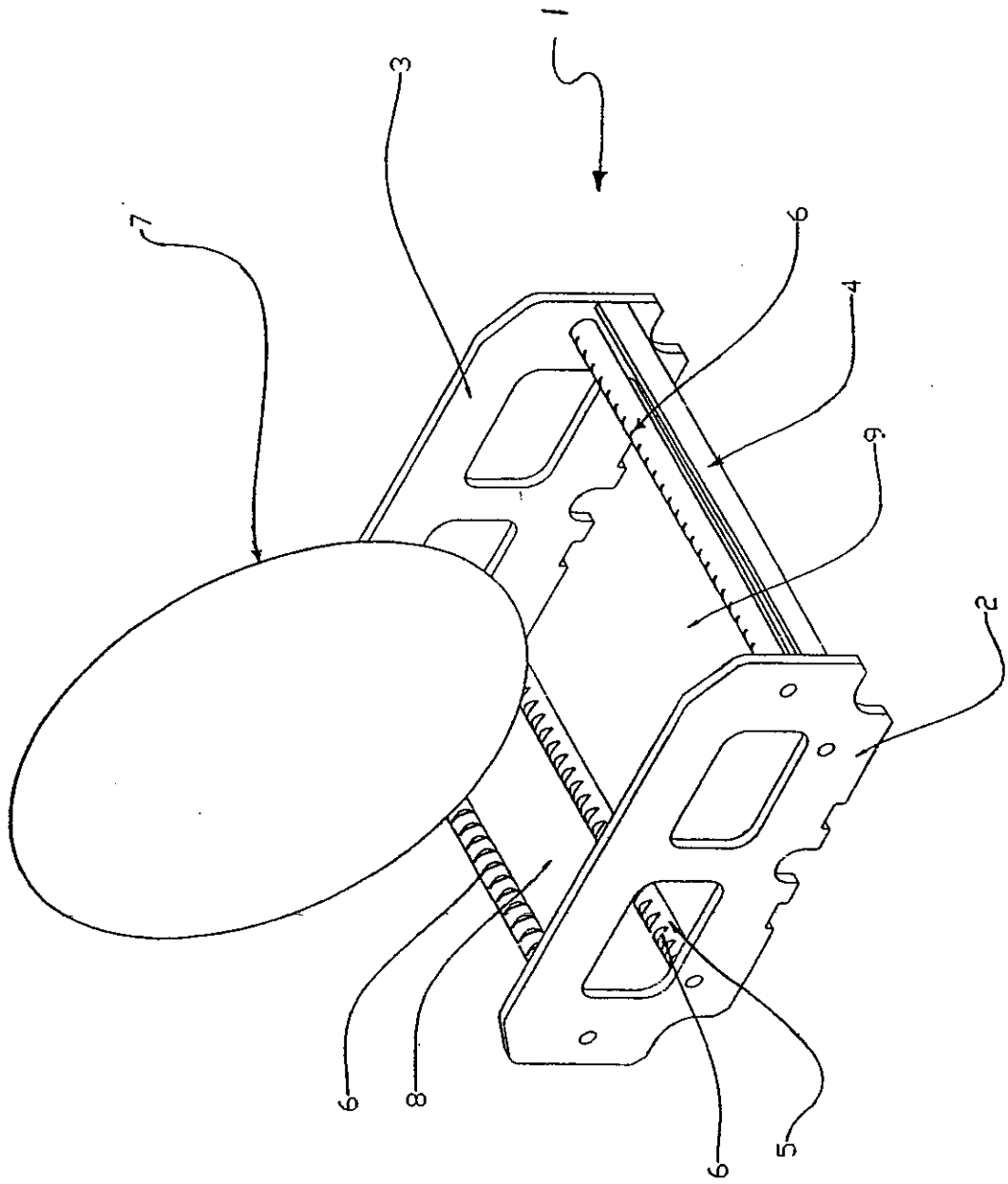


FIGURE 1

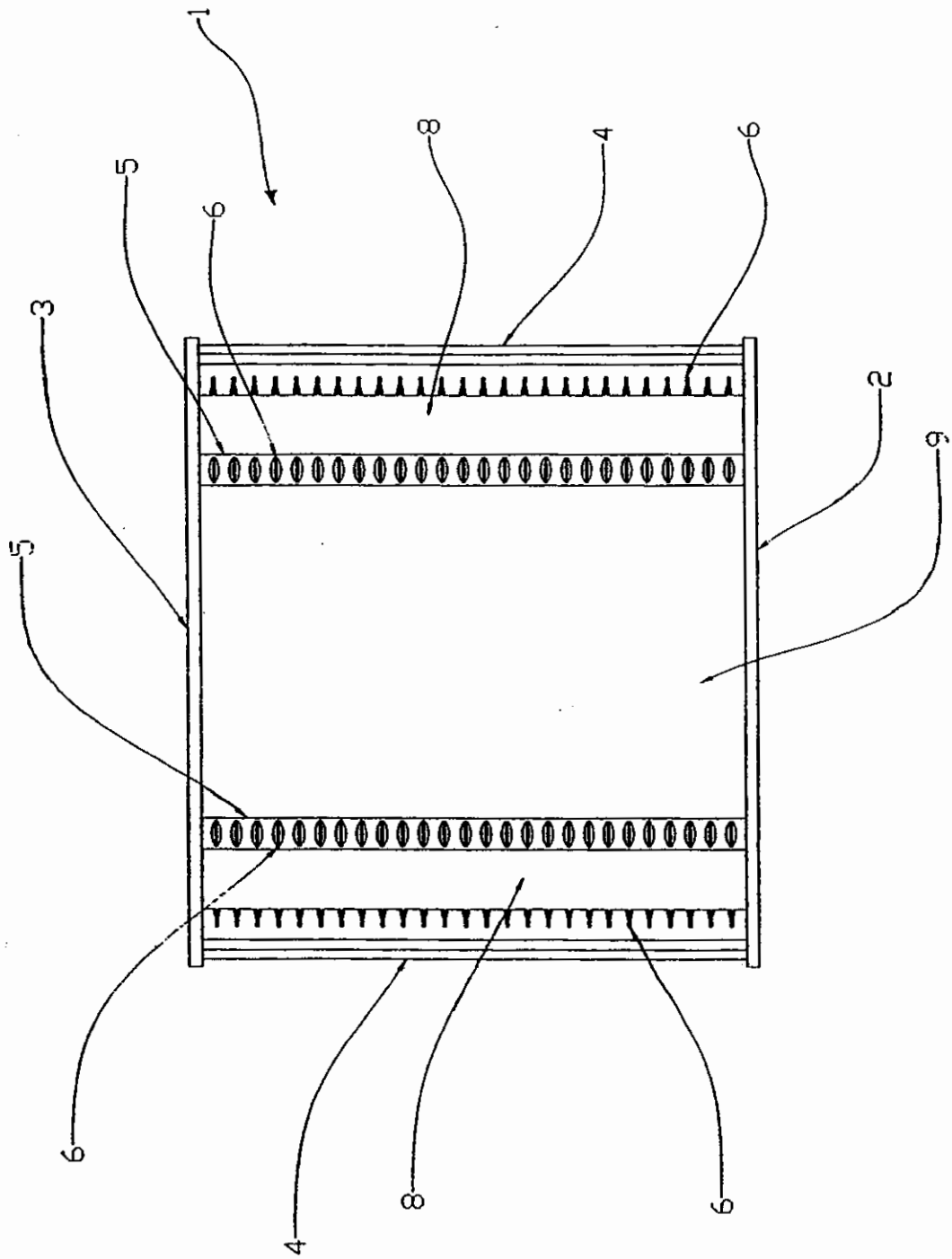


FIGURE 2

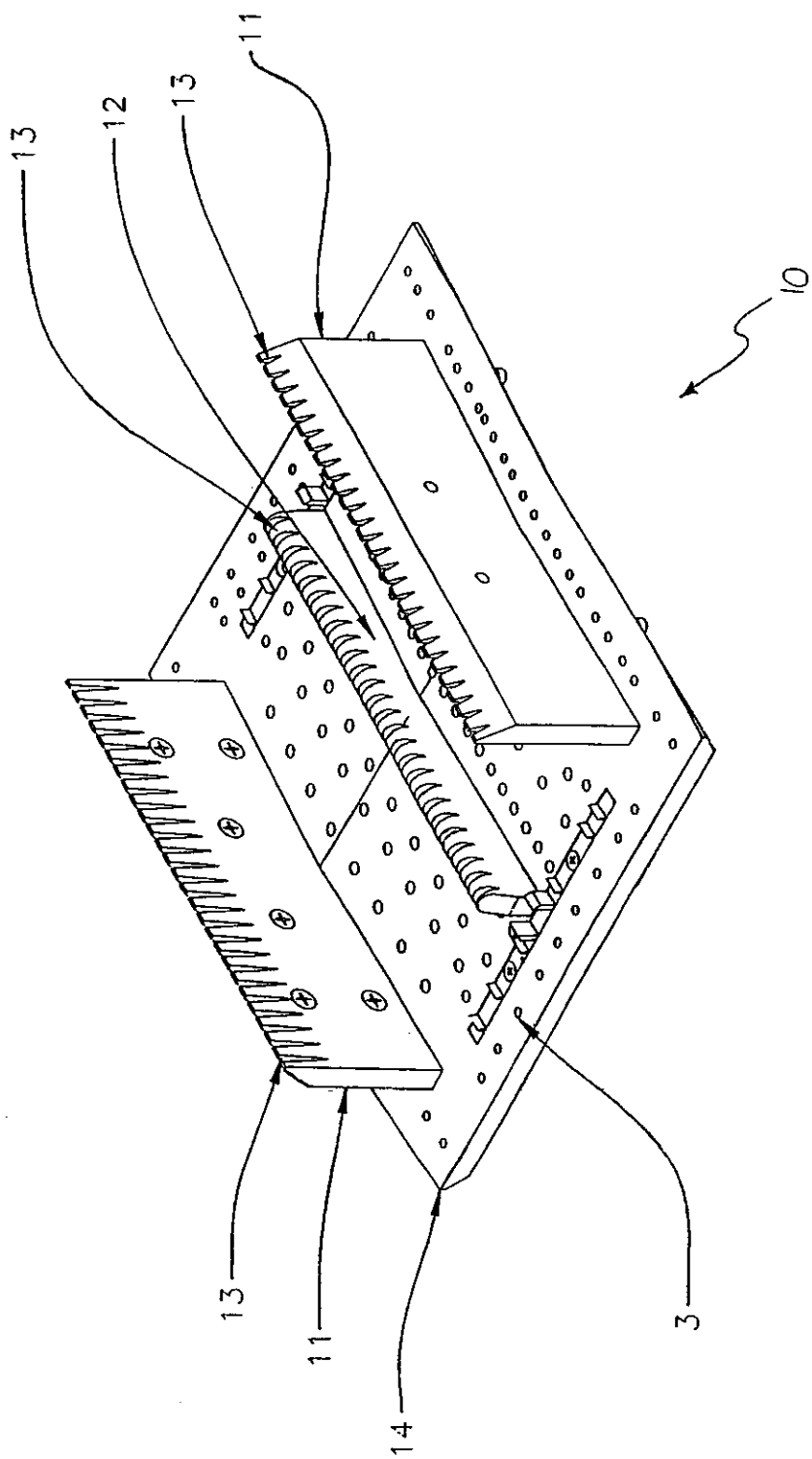


FIGURE 3

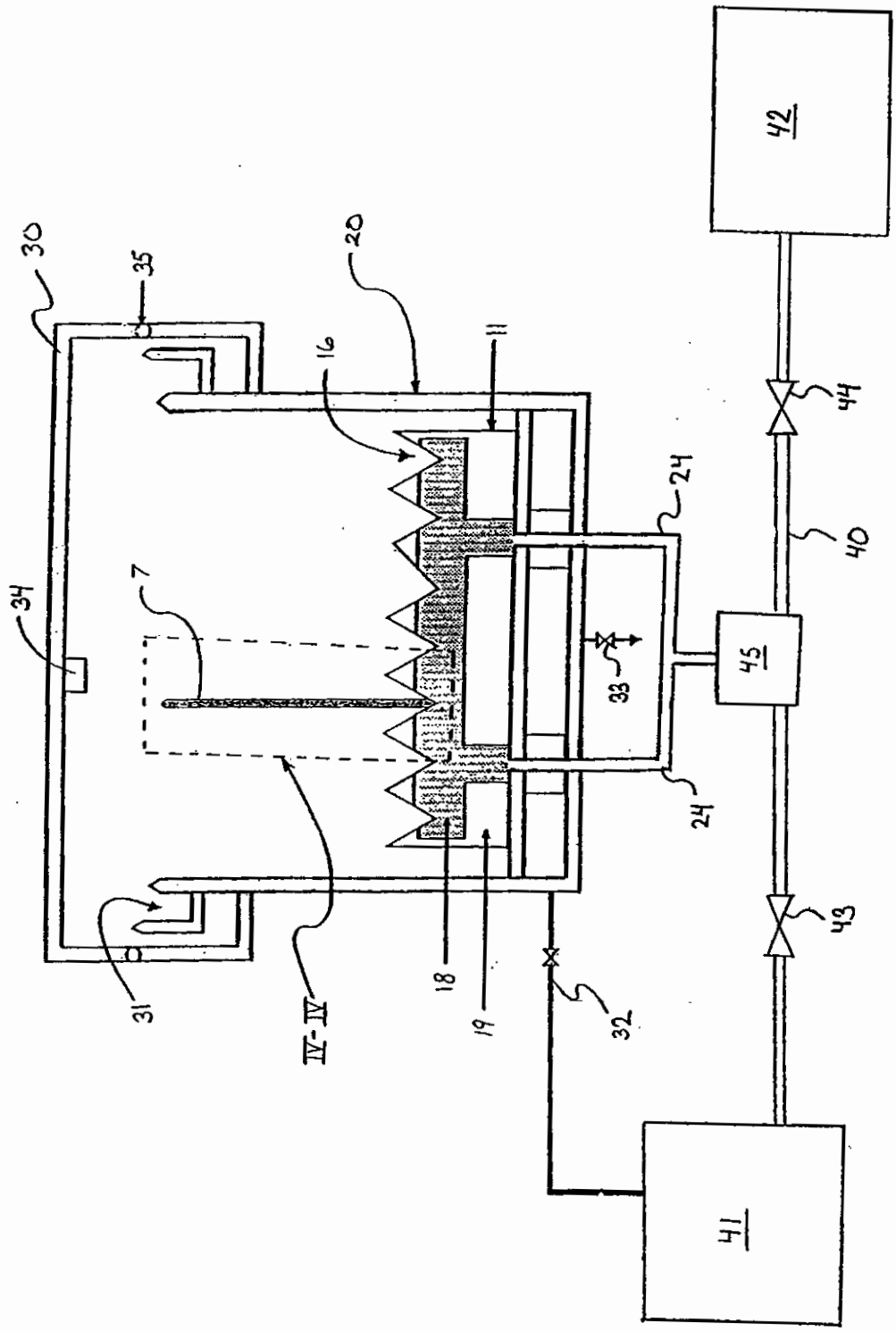


FIGURE 4

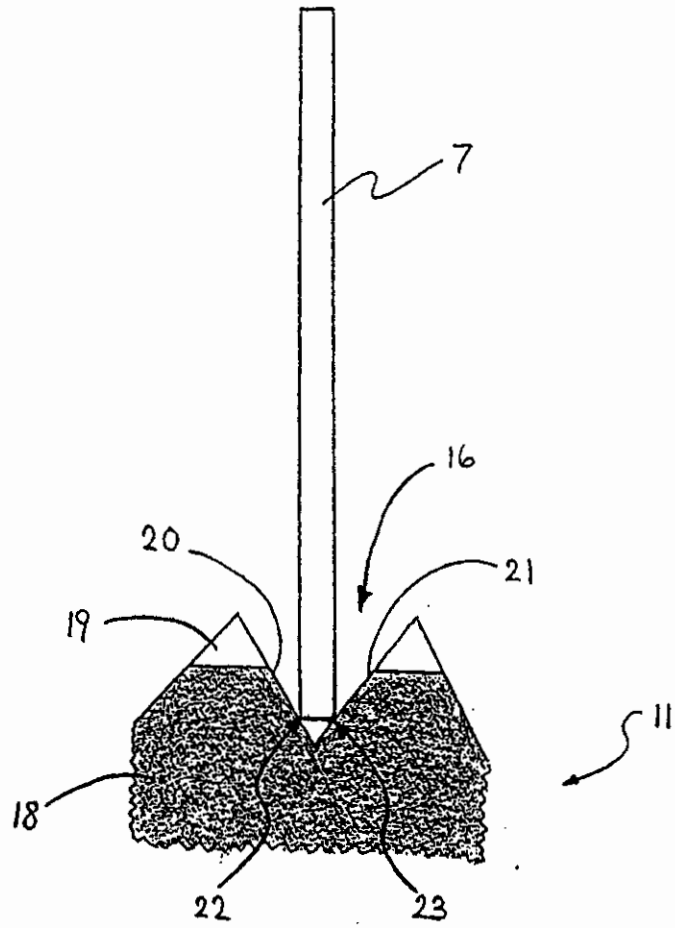


FIGURE 5

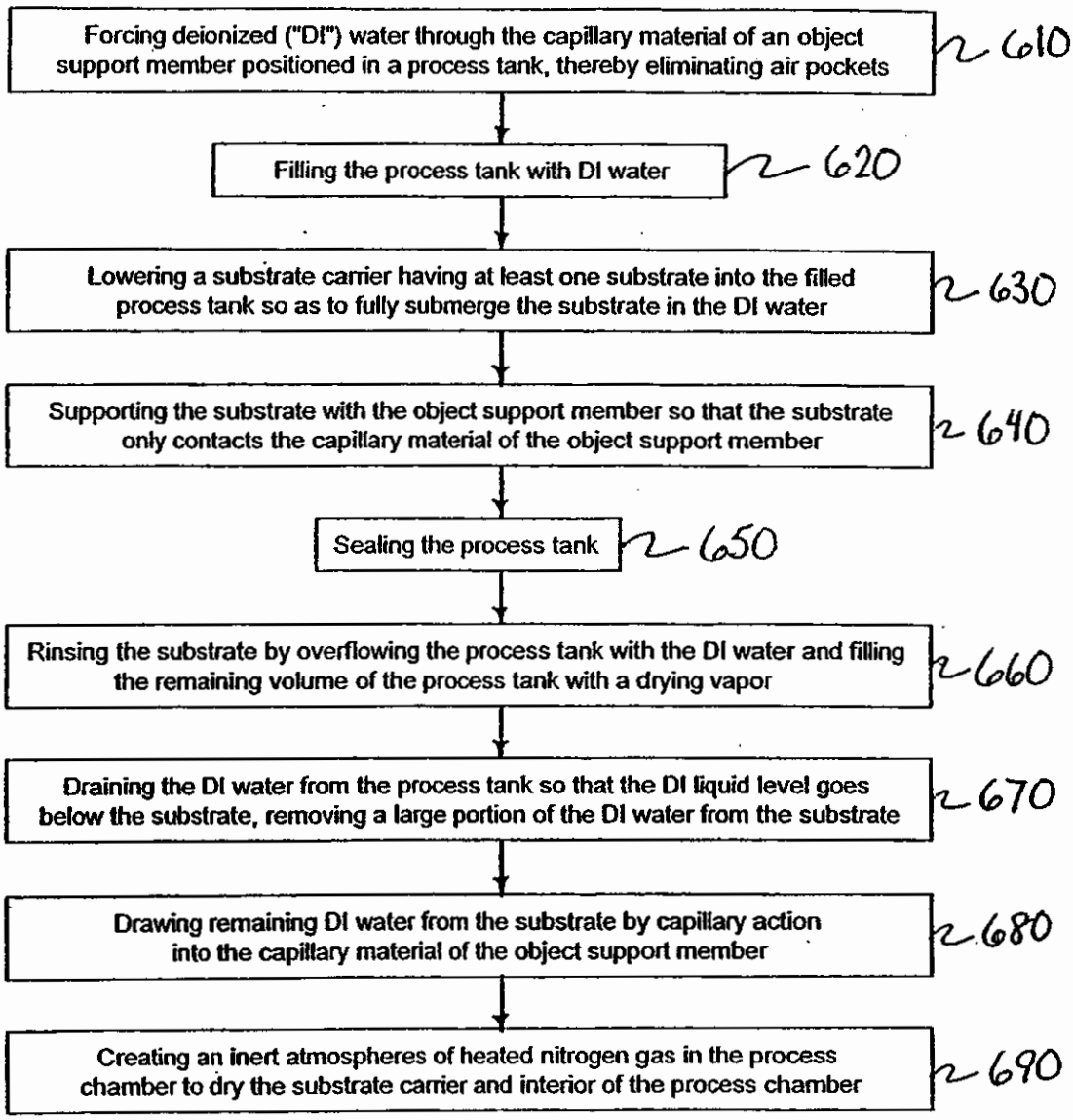

Forcing deionized ("DI") water through the capillary material of an object support member positioned in a process tank, thereby eliminating air pockets
610
Filling the process tank with DI water
620
Lowering a substrate carrier having at least one substrate into the filled process tank so as to fully submerge the substrate in the DI water
630
Supporting the substrate with the object support member so that the substrate only contacts the capillary material of the object support member
640
Sealing the process tank
650
Rinsing the substrate by overflowing the process tank with the DI water and filling the remaining volume of the process tank with a drying vapor
660
Draining the DI water from the process tank so that the DI liquid level goes below the substrate, removing a large portion of the DI water from the substrate
670
Drawing remaining DI water from the substrate by capillary action into the capillary material of the object support member
680
Creating an inert atmospheres of heated nitrogen gas in the process chamber to dry the substrate carrier and interior of the process chamber
690

FIGURE 6